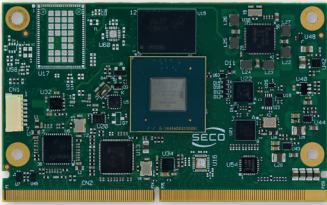




SOM-SMARC-MX95

SMARC® Rel. 2.1.1 module with NXP i.MX 95 Applications Processors

Optimized processing and advanced ML acceleration for next-generation computing



HIGHLIGHTS



CPU

NXP i.MX 95: 6x Cortex-A55 @2GHz, 1x M33 core @333MHz, 1x M7 core @800MHz



CONNECTIVITY

2x GbE, optional Wi-Fi + BT/BLE module, support for 3rd 10Gbps interface



MULTIMEDIA

2D/3D GPU and NPU ML accelerator up to 2.0 TOP/s



MEMORY

Up to 16GB LPDDR5

Available in Industrial Temperature Range



MAIN FIELDS OF APPLICATION



Transportation



Industrial Automation



Smart Devices

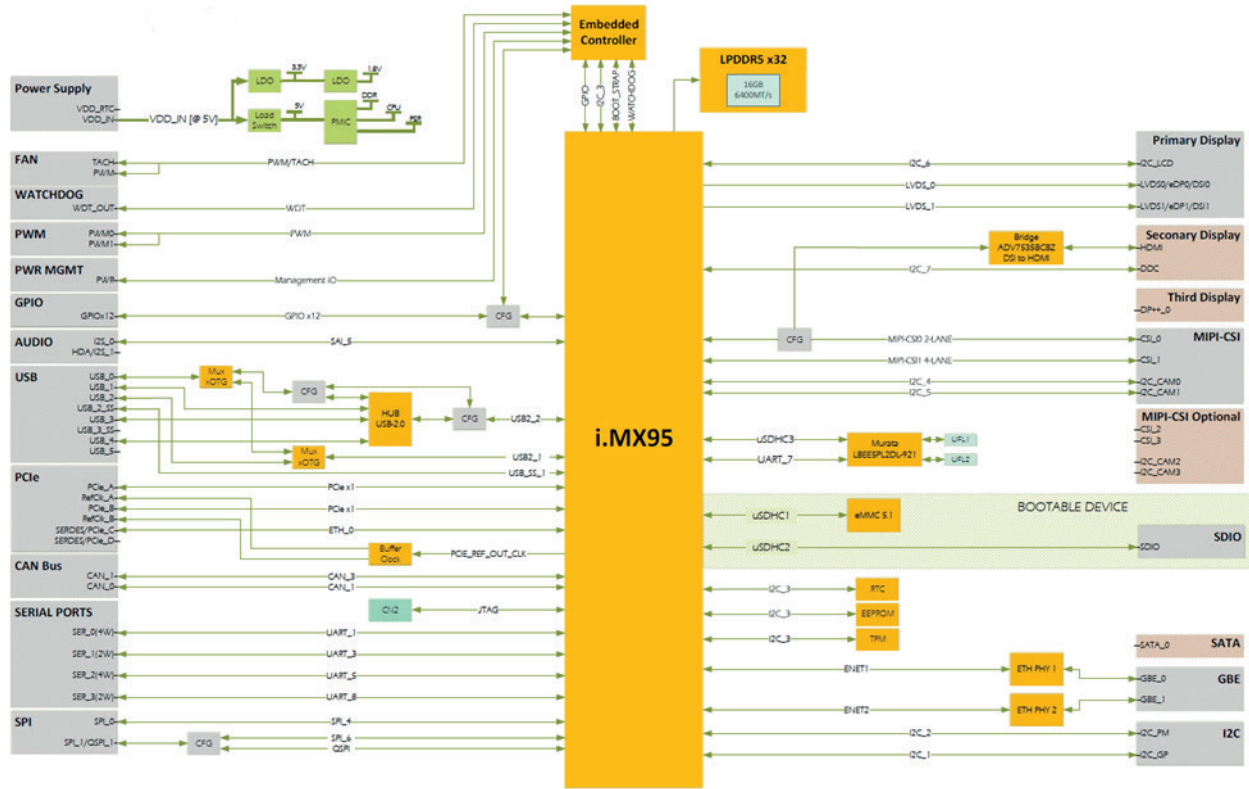


Smart Buildings & Smart Cities

FEATURES

Processor	NXP i.MX95 Applications Processors <ul style="list-style-type: none"> 6x Arm® Cortex™-A55 @2GHz Arm® Cortex™-M33 @333Mhz Arm® Cortex®-M7 @800Mhz 	Serial Ports	2x UART (4-wires) 2x UART (2-wires)
System Memory	Up to 16GB LPDDR5 6.4GT/s (32-bit)	CAN Bus	2x CAN interfaces
NPU	2.0 TOP/s Neural Network performance, up to 1.0 GHz	Other Interfaces	2x general purpose PWM FAN Management Signals Up to 12x GPIOs 1x general purpose I2C bus 1x power management I2C bus 1x general purpose SPI interface 1x QuadSPI interface or additional general purpose SPI interface
Video Interfaces	2x LVDS single channel / 1xLVDS dual channel Optional HDMI® interface 1x 4-lanes CSI camera interface Optional 1x 2-lanes CSI camera interface (alternative to HDMI® interface)		Watchdog Boot select signals Power management signals JTAG Header Optional TPM 2.0 soldered on-board
Video Resolution	LVDS, HDMI®: up to 1080p @60Hz		Power Supply
Graphics	GPU Arm Mali-G310 V2 with 2D/3D acceleration	Operating System	Linux Yocto
Mass Storage	Up to 128GB eMMC 5.1 drive soldered on-board (boot device) SD 4-bit interface (boot device)	Operating Temperature*	0 ÷ +60°C (Commercial Range) -40 ÷ +85°C (Industrial Range)
Networking	Up to 2x Gigabit Ethernet interfaces Optional Wi-Fi (802.11a/b/g/n/ac/ax) + BT/BLE 5.3 module soldered on-board SERDES (XGMII) interface for additional third Ethernet interface, up to 10Gbps supported	Dimensions	82 x 50 mm
USB	Up to 5x USB 2.0 host ports 1x USB SuperSpeed 5Gbps port Up to 1x USB 2.0 OTG port	*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.	
PCI-e	Up to 2x PCI-e x1 Gen3 ports		
Audio	1x I2S audio interface		

BLOCK DIAGRAM



Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DATA ORCHESTRATION

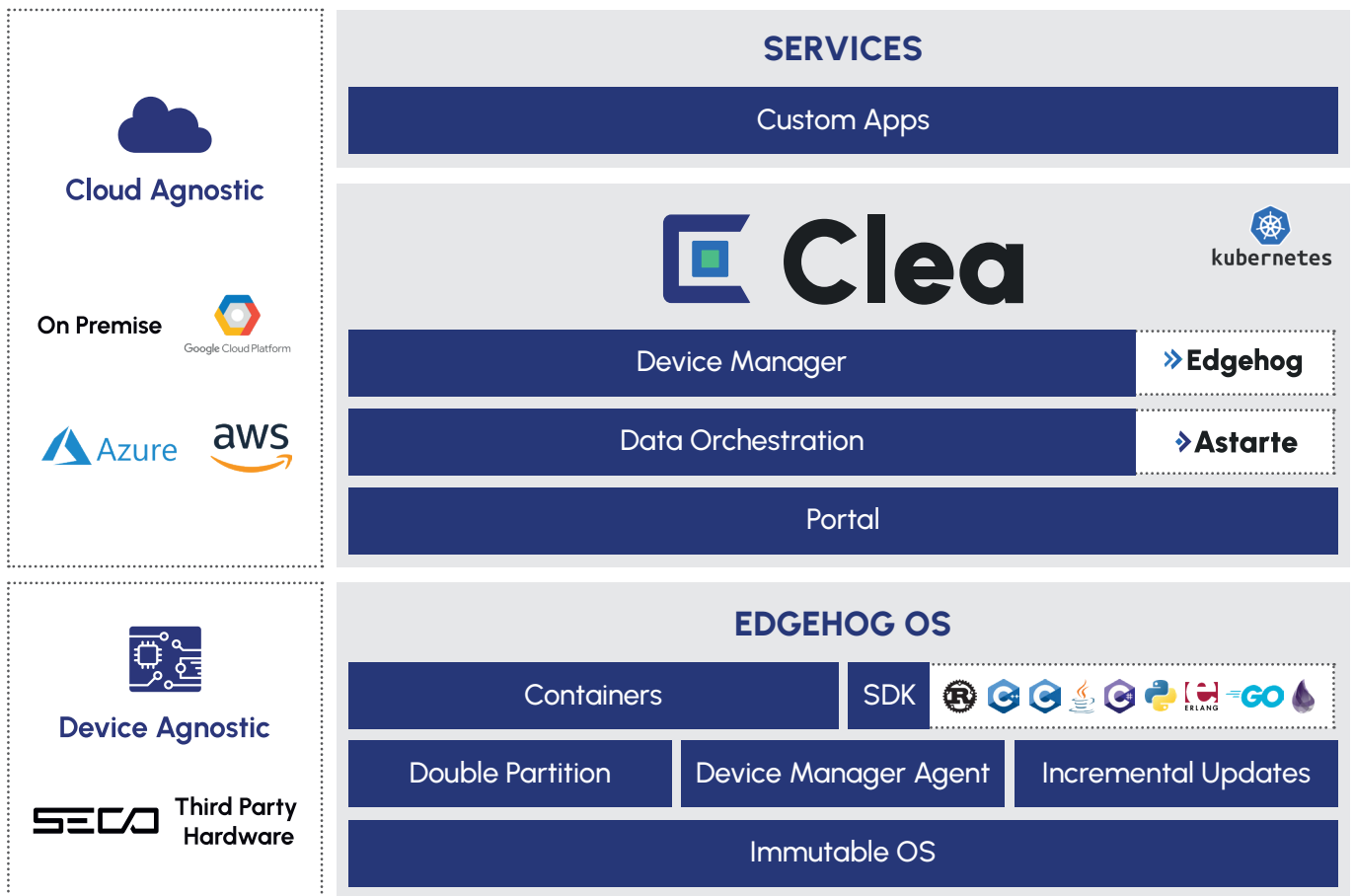
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



Scan to know more about our solution

EDGEHOG OS



CLEA DOCS

